SWITCHMODE Power Rectifier

Features and Benefits

- Low Forward Voltage
- Low Power Loss / High Efficiency
- High Surge Capacity
- 175°C Operating Junction Temperature
- 20 A Total (10 A Per Diode Leg)
- Pb-Free Package is Available*

Applications

- Power Supply Output Rectification
- Power Management
- Instrumentation

Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets UL 94, V-0 @ 0.125 in
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Rating: Human Body Model = 3B

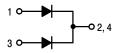
Machine Model = C

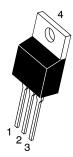


ON Semiconductor®

www.onsemi.com

SCHOTTKY BARRIER RECTIFIER 20 AMPERES, 45 VOLTS









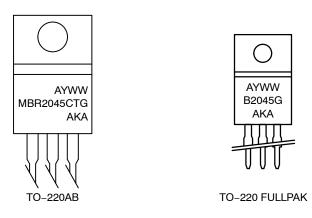
TO-220 FULLPAK™ CASE 221D STYLE 3

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 2 of this data sheet.

ORDERING INFORMATION

See detailed ordering and shipping information on page 3 of this data sheet.



= Assembly Location

= Year WW = Work Week G = Pb-Free Package **AKA** = Diode Polarity

Figure 1. Marking Diagrams

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	45	V
Average Rectified Forward Current Per Device Per Diode (T _C = 165°C)	I _{F(AV)}	20 10	А
Peak Repetitive Forward Current per Diode Leg (Square Wave, 20 kHz, T _C = 163°C)	I _{FRM}	20	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	150	А
Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz) See Figure 13	I _{RRM}	1.0	Α
Storage Temperature Range	T _{stg}	-65 to +175	°C
Operating Junction Temperature (Note 1)	TJ	-65 to +175	°C
Voltage Rate of Change (Rated V _R)	dv/dt	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The heat generated must be less than the thermal conductivity from Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

Characteristic		Symbol	Value	Unit
Maximum Thermal Resistance				°C/W
(MBR2045CT)	Junction-to-Case	$R_{ hetaJC}$	2.0	
	Junction-to-Ambient	$R_{ hetaJA}$	60	
(MBRF2045CT)	Junction-to-Case	$R_{ hetaJC}$	4.75	
	Junction-to-Ambient	$R_{\theta JA}$	75	

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Instantaneous Forward Voltage (Note 2)	VF				V
(i _F = 10 A, T _J = 125°C)		_	0.50	0.57	
(i _F = 20 A, T _J = 125°C)		_	0.67	0.72	
(i _F = 20 A, T _J = 25°C)		-	0.71	0.84	
Instantaneous Reverse Current (Note 2)	i _R				mA
(Rated dc Voltage, T _J = 125°C)		_	10.4	15	
(Rated dc Voltage, T _J = 25°C)		_	0.02	0.1	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width = 300 µs, Duty Cycle ≤ 2.0%.

ORDERING INFORMATION

Device Order Number	Package Type	Shipping [†]
MBR2045CTG	TO-220 (Pb-Free)	50 Units / Rail
MBRF2045CTG	TO-220FP (Pb-Free)	50 Units / Rail

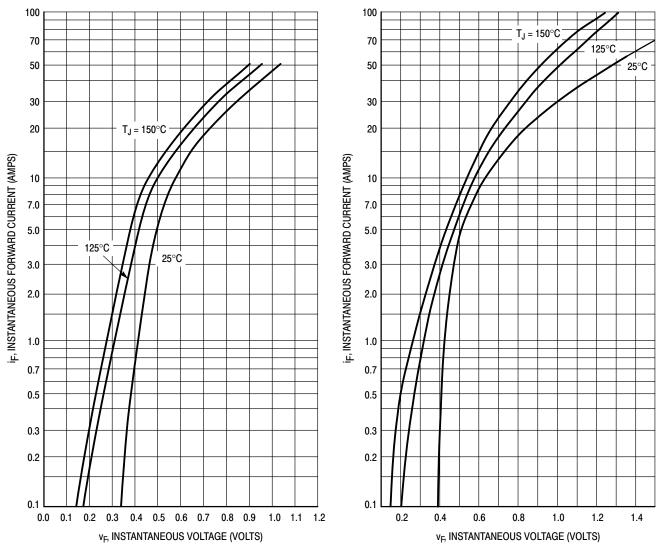
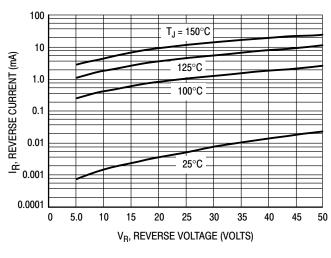


Figure 1. Typical Forward Voltage

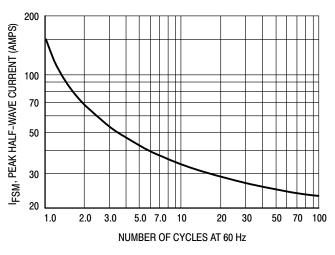
Figure 2. Maximum Forward Voltage



100 $T_J = 150^{\circ}C$ 10 125°C I_R, REVERSE CURRENT (mA) 10.0 1.0 0.1 0.1 100°C 1.0 75°C 25°C 0.001 0 5.0 10 15 20 25 30 35 40 45 50 V_R, REVERSE VOLTAGE (VOLTS)

Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current



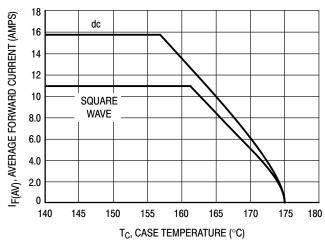
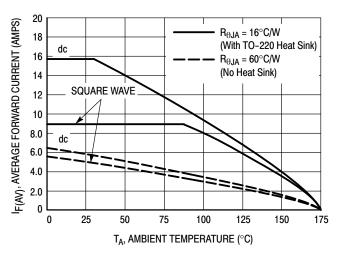


Figure 5. Maximum Surge Capability

Figure 6. Current Derating, Case, Per Leg



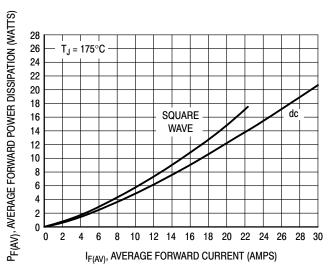


Figure 7. Current Derating, Ambient, Per Leg

Figure 8. Forward Power Dissipation

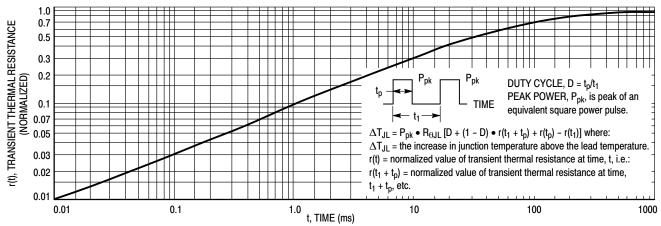


Figure 9. Thermal Response for MBR2045CT

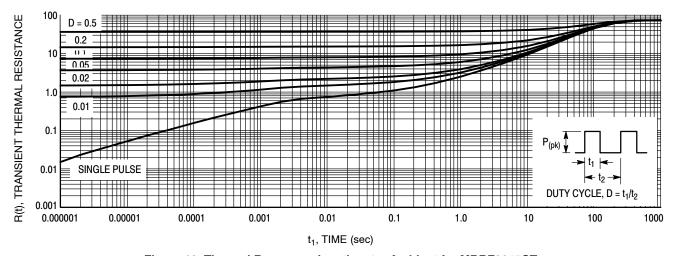


Figure 10. Thermal Response Junction-to-Ambient for MBRF2045CT

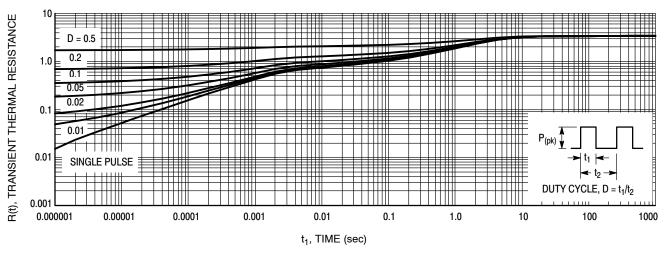


Figure 11. Thermal Response Junction-to-Case for MBRF2045CT

HIGH FREQUENCY OPERATION

Since current flow in a Schottky rectifier is the result of majority carrier conduction, it is not subject to junction diode forward and reverse recovery transients due to minority carrier injection and stored charge. Satisfactory circuit analysis work may be performed by using a model consisting of an ideal diode in parallel with a variable capacitance. (See Figure 12.)

Rectification efficiency measurements show that operation will be satisfactory up to several megahertz. For example, relative waveform rectification efficiency is approximately 70 percent at 2.0 MHz, e.g., the ratio of dc power to RMS power in the load is 0.28 at this frequency, whereas perfect rectification would yield 0.406 for sine wave inputs. However, in contrast to ordinary junction diodes, the loss in waveform efficiency is not indicative of power loss; it is simply a result of reverse current flow through the diode capacitance, which lowers the dc output voltage.

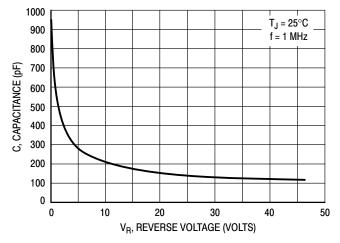


Figure 12. Typical Capacitance

+150 V, 10 mAdc

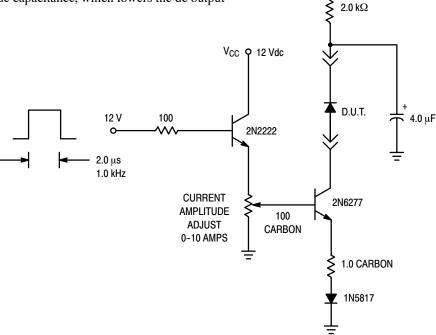
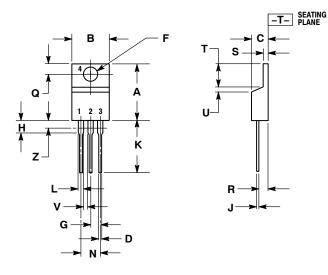


Figure 13. Test Circuit for dv/dt and Reverse Surge Current

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AH**



NOTES:

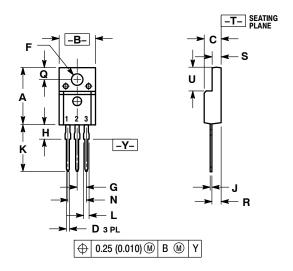
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
С	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

PIN 1. ANODE 2. CATHODE

- ANODE CATHODE

TO-220 FULLPAK CASE 221D-03 **ISSUE K**



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH
- 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.
 - INCHES MILLIMETERS DIM MIN MAX MIN MAX
 A
 0.617
 0.635
 15.67
 16.12

 B
 0.392
 0.419
 9.96
 10.63
 0.177 0.193 4.50 4.90 D 0.024 0.039 0.60 1.00 F 0.116 0.129 2.95 3.28 0.100 BSC 2.54 BSC H 0.118 0.135 3.00 3.43 J 0.018 0.025 0.45 0.63 K 0.503 0.541 12.78 13.73 L 0.048 0.058 1.23 1.47 N 0.200 BSC 5.08 BSC Q 0.122 0.138 3.10 3.50 R 0.099 0.117 2.51 2.96 S 0.092 0.113 2.34 2.87 U 0.239 0.271 6.06 6.88

- PIN 1. ANODE 2. CATHODE 3. ANODE

FULLPAK is a trademark of Semiconductor Components Industries, LLC.

ON Semiconductor and the interpretability are registered trademarks of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries. SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negl

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5817-1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor: MBRF2045CTG